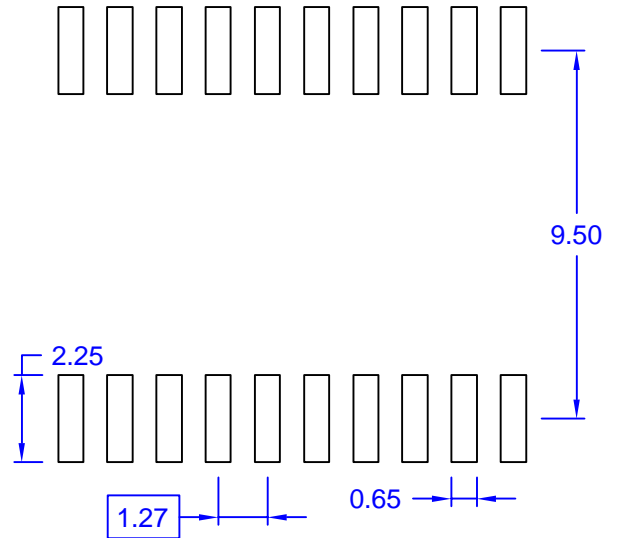
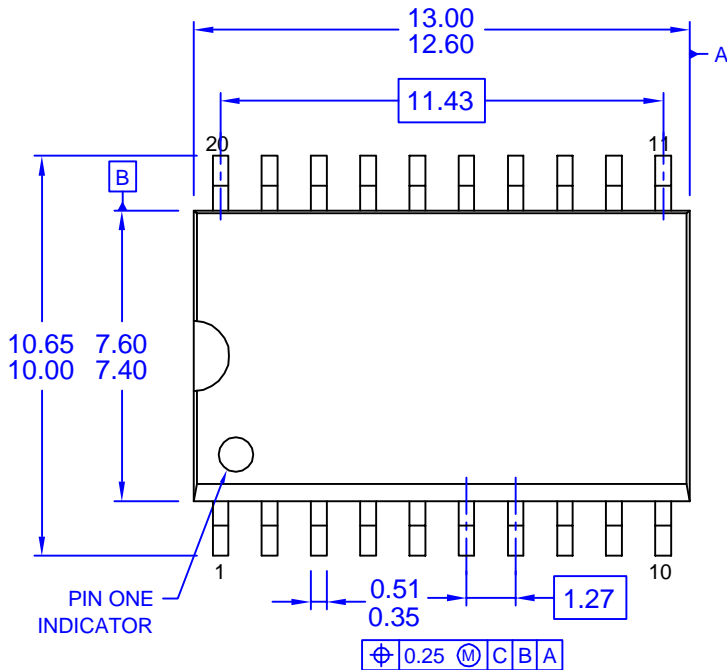
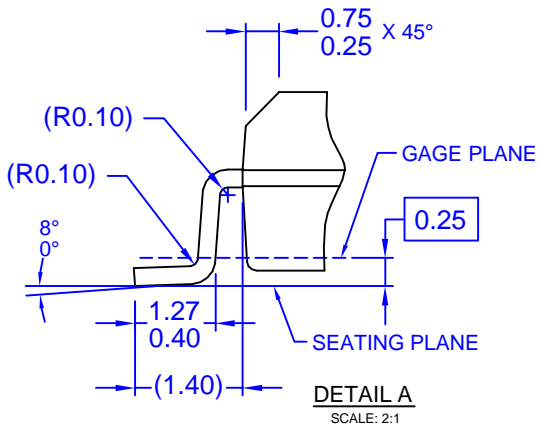
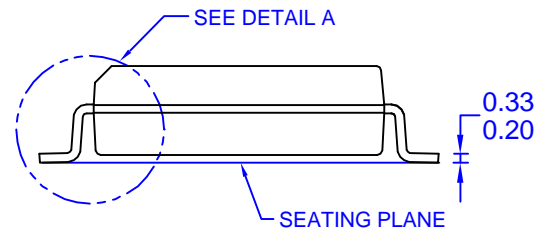
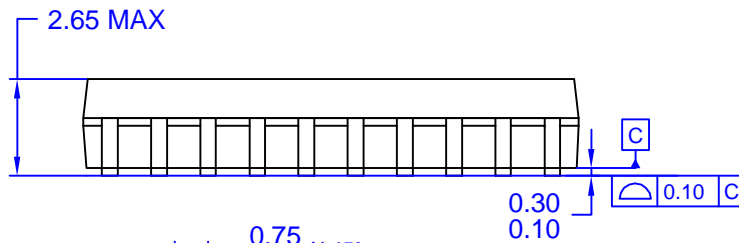


REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
F	NEW MARKTING DWG.		Jan-1999	FEITAN
2	UPDATED DWG. TO CURRENT STD. FORMAT.		14-Mar-2007	J Chan
3	ADOPTED JEDEC LEADSPREAD VALUE	ECN-MKT-M20BR3	31 JULY 07	L.HUEBENER



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-013, VARIATION AC, ISSUE E
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) CONFORMS TO ASME Y14.5M-1994
- E) LANDPATTERN STANDARD: SOIC127P1030X265-20L
- F) DRAWING FILENAME: MKT-M20BREV3

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN L.HUEBENER	31 JULY 07	20LD, SOIC, JEDEC MS-013, 0.300" WIDE BODY			
DFTG. CHK. H.ALLEN	2 AUG 2007				
ENGR. CHK.					
		SCALE N/A	SIZE C	DRAWING NUMBER MKT-M20B	REV 3
		DO NOT SCALE DRAWING		SHEET 1 of 1	